PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Yu-Rung Hsu	01/12/2011
Chen-Hua Yu	01/12/2011
Chao-Cheng Chen	01/12/2011
Ming-Huan Tsai	01/12/2011
Hsien-Hsin Lin	01/12/2011
Hsueh-Chang Sung	01/12/2011

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12645834

OP $40.00 12645834

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	2009-0352/24061.1326

NAME OF SUBMITTER:	David M. O'Dell
Total Attachments: 3 source=1326Assignment#page1.tif source=1326Assignment#page2.tif source=1326Assignment#page3.tif	

Docket No.: 2009-0352 / 24061.1326
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1) Yu-Rung Hsu of 7F-1, No. 2, Lane 12, Daxue Road, East District
Tainan City 701, Taiwan, R.O.C.

(2) Chen-Hua Yu of No. 3, 38 Waterfront Road 2
Hsin-Chu, Taiwan, R.O.C.

(3) Chao-Cheng Chen of #46 3F-2, Lui-Sui Road
Shin-Chu City, Taiwan, R.O.C.

(4) Ming-Huan Tsai of 8F., No.41, Guangming 6th Rd., Zhubei City,
Hsinchu County, Taiwan (R.O.C.)

(4) Hsien-Hsin Lin of 11F-2, No. 21, 23 Lane, Guan-Dong Rd.
Hsinchu City, Taiwan (R.O.C.)

(6) Hsueh-Chang Sung of 3F., No.208, Wencai St., Zhubei City,
Hsinchu County 302, Taiwan (R.O.C.)

have invented certain improvements in

METHOD OF FABRICATING STRAINED STRUCTURE IN SEMICONDUCTOR DEVICE

for which we filed an application for Letters Patent of the United States of America on December 23, 2009, as U.S. Serial No. 12/645,834; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yu-Rung Hsu

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Dated: Jan 12, 2011

Inventor Signature

Inventor Name: Chen-Hua Yu

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Dated: 1/12/11

Inventor Signature

Inventor Name: Chao-Cheng Chen

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Dated: 1/12, 2011

Inventor Signature

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Dated: 1/12 2011

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Dated: 1/12, 2011

Hsien Hsin Lin
Inventor Signature

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Dated: 1/12 . 2011

Hsueh-Chang Sung
Inventor Signature
